

MATERIAL DECLARATION SHEET



Material Number	CM322522 Series			
Product Line	Wound Chip Inductor			
Compliance Date	2020 / 10 / 29			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite Material	T2F	0.01	Iron oxide (Fe2O3)	1309-37-1	63.0	12.60	20.00
				Nickel oxide (NiO)	1313-99-1	12.0	2.40	
				Zinc oxide (ZnO)	1314-13-2	18.0	3.60	
				Copper oxide(CuO)	1317-38-0	7.0	1.40	
2	Winding Wire	P180	0.01	Copper (Cu)	7440-50-8	95.0	19.00	20.00
				Polyester Resin	9009-54-5	5.0	1.00	
3	Terminal	Tc Lead	0.02	Copper (Cu)	7440-50-8	95.0	38.00	40.00
				Tin (Sn)	7440-31-5	5.0	2.00	
4	Adhesive	S-F1-610W	0.0014	BISPHENOL A DIGLYCIDYL ETHER RESIN	25068-38-6	65.0	1.82	2.80
				Dicyanodiamide	461-58-5	6.0	0.17	
				Accelerant	-	6.0	0.17	
				Titanium dioxide	13463-67-7	4.0	0.11	
				Silicon dioxide	731-86-9	19.0	0.53	

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5	Adhesive	1010-42A	0.0024	Bisphenol A diglycidyl ether	25068-38-6	81.0	3.89	4.80
				1,4-Butanediol diglycidyl ether	2425-79-8	18.0	0.86	
				Additives	-	1.0	0.05	
		5524-2B	0.0012	Methyltetrahydrophthalic anhydride	26590-20-5	95.0	2.28	2.40
				2,4-dimethyl-1H-imidazole	930-62-1	5.0	0.12	
6	Molding Compound	1100RG	0.004	silica	60676-86-0	69.0	5.52	8.00
				Antimony Trioxide	1309-64-4	2.5	0.20	
				Formaldehyde, polymer with 2-(chloromethyl)oxirane and 2-methylphenol	29690-82-2	15.0	1.20	
				Phenol-Formaldehyde Resin	9003-35-4	10.0	0.80	
				Brominated epoxy resin	40039-93-8	2.5	0.20	
				Carbon black	1333-86-4	1.0	0.08	
7	Solder	100H	0.001	Tin (Sn)	7440-31-5	100.0	2.00	2.00
			Total weight					0.050

This Document was updated on: **2020/10/29**

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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- a. "Compliance Date" is not the date supplier submits the MDS, but when the product was first compliant with RoHS.
- b. "This Document was updated on:" is where we indicate when supplier submits the MDS. All previous MDS must be archived for traceability in the future.
- c. Material weights for components less than 100mg (most Semiconductor products) should be listed in milligrams. This avoids all those zeros and round off issues.